

Title (en)  
METHOD FOR PRODUCING A SUPPORTING ELEMENT FOR AN INTEGRATED CIRCUIT MODULE FOR PLACEMENT IN CHIP CARDS

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES TRÄGERELEMENTS FÜR EINEN IC-BAUSTEIN ZUM EINBAU IN CHIPKARTEN

Title (fr)  
PROCEDE DE PRODUCTION D'UN ELEMENT DE SUPPORT POUR UN MODULE CIRCUIT INTEGRE A MONTER DANS UNE CARTE A PUCE

Publication  
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Application  
**EP 99955820 A 19990930**

Priority  
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• DE 19845665 A 19981005

Abstract (en)  
[origin: DE19845665A1] The invention relates to a method for producing a supporting element (4) for an integrated circuit module (7) for placement in chip cards (1), whereby the supporting element (4) comprises conductive contact surfaces (5) situated on an electrically insulating plastic substrate (10). Said contact surfaces are connected in a conductive manner to corresponding connecting points (8) of the integrated circuit module (7). In a first step, a plastic substrate (10) is provided with recesses (11) which correspond to the connecting points (8) of the integrated circuit module (7). In a second step, the integrated circuit module (7) is fixed with the side thereof comprising the connecting points (8) on the plastic substrate (10) in such a way that the connecting points (8) are arranged (10) in a positionally accurate manner with regard to the recesses (11) in the plastic substrate (10). In a third step, the electrically conductive contact surfaces (5) are produced via the recesses (11) in the plastic substrate (10) while forming electrically conductive connections (20) to the connecting points (8) of the integrated circuit module (7). This is achieved, while using a diffusion mask (12) and by depositing a metal (19) from the gas phase or by applying a conductive paste/liquid onto the regions (13) of the plastic substrate (10) which are not covered by the diffusion mask (12).

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IPC 8 full level  
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